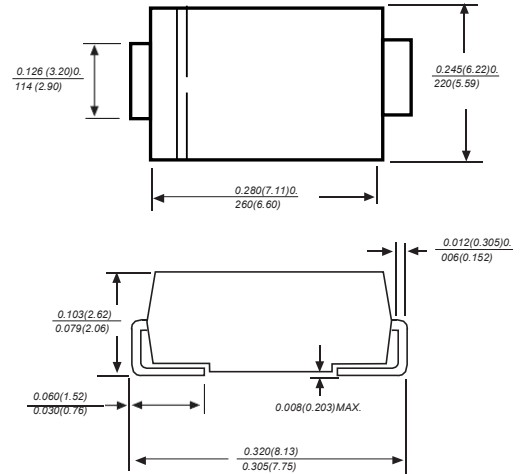


SURFACE MOUNT FAST RECOVERY RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Open Junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 250°C / 10 seconds at terminals
- ◆ Glass passivated chip junction

DO-214AB/SMC



Dimensions in inches and (millimeters)

Mechanical Data

Case : JEDEC DO-214AB/SMC Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0077 ounce, 0.22 grams

Maximum Ratings And Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	RS3AC	RS3BC	RS3DC	RS3GCC	RS3JCC	RS3KCC	RS3MC	UNITS
		RCD RS3AC	RCD RS3BC	RCD RS3DC	RCD RS3GC	RCD RS3JC	RCD RS3KC	RCD RS3MC	
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{bc}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{(AV)}$	3.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	90							A
Maximum instantaneous forward voltage at 3.0A	V_F	1.30							V
Maximum DC reverse current $T_A=25^\circ C$ at rated DC blocking voltage $T_A=125^\circ C$	I_R	5.0 100.0							μA
Maximum reverse recovery time (NOTE 1)	t_{rr}	150				250	500	ns	
Typical junction capacitance (NOTE 2)	C_J	40.0							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$ $R_{\theta JC}$	45.0 15.0							$^\circ C/W$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							$^\circ C$

Note: 1. Reverse recovery condition $I_F=0.5A, I_R=1.0A, t_{rr}=0.25A$
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.3.
 P.C.B. mounted with 2.0"x2.0" (5.0x5.0cm) copper pad areas

DN:T21315A1

Fig.1 Maximum Average Forward Current Rating

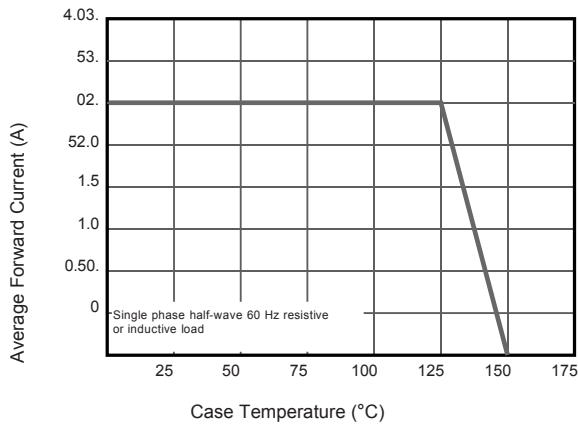


Fig.2 Typical Reverse Characteristics

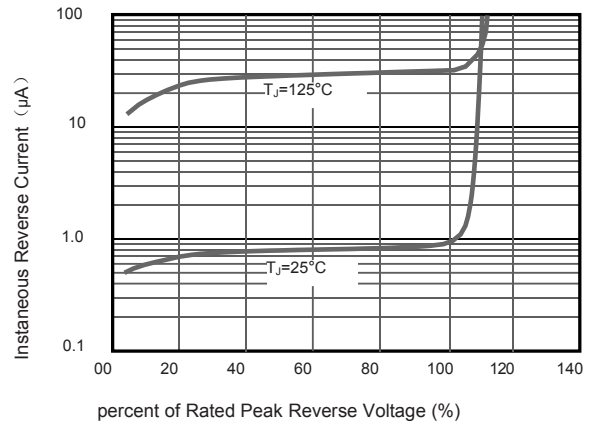


Fig.3 Typical Instantaneous Forward Characteristics

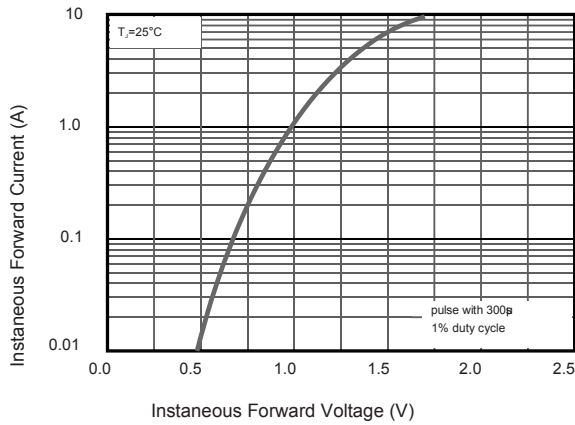


Fig.4 Typical Junction Capacitance

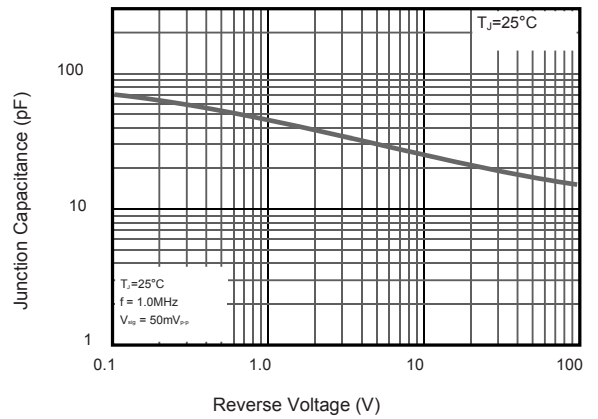
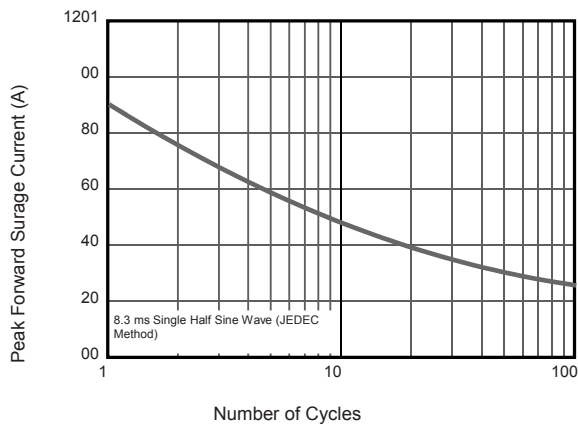
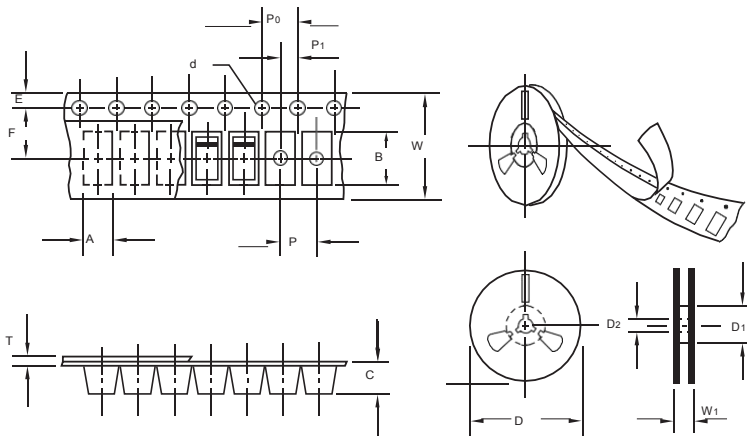


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



The curve above is for reference only.



unit:mm

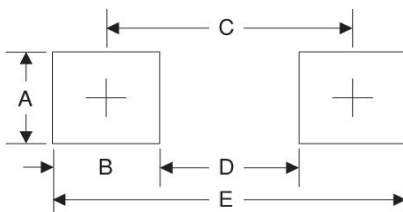
Item	Symbol	Tolerance	SMC
Carrier width	A	0.1	6.15
Carrier length	B	0.1	8.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	16.00
Reel width	W1	1.0	16.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMC	13"	3,000	4.0	6000	190*190*41	330	365*365*340	42000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	4.3	0.170
B	4.1	0.160
C	7.9	0.311
D	3.8	0.150
E	12	0.472